



Material Content Data Sheet



Sales Product Name		IPW90R500C3		Issued		29. August 2013		
MA#		MA000468410						
Package		PG-TO247-3-41		Weight*		6047.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	9.945	0.16	0.16	1644	1644
leadframe	non noble metal	iron	7439-89-6	3.972	0.07		657	
	inorganic material	phosphorus	7723-14-0	1.192	0.02		197	
	non noble metal	copper	7440-50-8	3967.071	65.59	65.68	655951	656806
wire	non noble metal	aluminium	7429-90-5	4.076	0.07	0.07	674	674
encapsulation	organic material	carbon black	1333-86-4	19.973	0.33		3303	
	plastics	epoxy resin	-	379.496	6.27		62749	
	inorganic material	silicondioxide	60676-86-0	1597.877	26.42	33.02	264208	330259
leadfinish	non noble metal	tin	7440-31-5	31.874	0.53	0.53	5270	5270
plating	non noble metal	nickel	7440-02-0	28.550	0.47	0.47	4721	4721
solder	non noble metal	tin	7440-31-5	2.459	0.04		407	
	noble metal	silver	7440-22-4	0.946	0.02		156	
	non noble metal	antimony	7440-36-0	0.378	0.01	0.07	63	626
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

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